

**Amendments to the Claims:**

The following claims will replace all prior versions of the claims in this application (in the unlikely event that no claims follow herein, the previously pending claims will remain):

1. (Currently amended) ~~Curable resin compositions based on~~ A curable resin composition comprising an unsaturated prepolymer, a vinyl ether monomer that can be cross-linked with it and one or more other monomers, ~~characterised in that wherein~~ the vinyl ether monomer is a vinyl ether having a general structure according to formula (I) or (II):



or



where

A represents hydrogen or an alkyl group with 1- 3 C atoms, and where, if there is more than one A, the individual A groups may be the same or different,

R either represents an aliphatic group, optionally branched, with 1-20 C atoms, which may also contain a cyclohexyl group and optionally in the carbon chain also one or more O and/or S atoms, which group may also be substituted with a functional group chosen from either a hydroxyl group or an amino group, optionally substituted with one or two alkyl groups with 1-3 C atoms,

or represents a polyethylene glycol or a polypropylene glycol with an average chain length of 2 to 10 glycol units, optionally with an aliphatic group with 1-5 C atoms attached to the chain's free hydroxyl group, and

R' either is a residual group that corresponds to an aliphatic group, optionally branched, with 2-20 C atoms, which may also contain a 1,4-dimethylenecyclohexyl group, or represents a polyethylene glycol or a polypropylene glycol with an average chain length of 2 to 10 glycol units, and

n is 1,2,3 or 4, and

where the unsaturated prepolymer is a (meth)acrylate-containing resin selected from the group consisting of vinyl esters resins and vinyl ester urethane resins obtained by reacting an isocyanate, a polyol and a hydroxyl-terminated ester of (meth)acrylic acid, and has an acid number of less than 10 mg of KOH per g, and where the curing is may be effected with the

aid of a radical-forming system that is unstable in the temperature range from -20°C to +110°C.

2. (Currently amended) Curable resin ~~compositions~~ composition according to Claim 1, ~~characterised in that~~ wherein the vinyl ether monomer is a mono-and/or divinyl ether monomer.

3. (Currently amended) Curable resin ~~compositions~~ composition according to Claim 2, ~~characterised in that~~ wherein the vinyl ether monomer ~~has been chosen from the group comprising~~ is butanediol divinyl ether, butyl vinyl ether, cyclohexanedimethanol divinyl ether, cyclohexanedimethanol monovinyl ether, diethylene glycol divinyl ether, ethylene glycol divinyl ether, 2-ethylhexyl divinyl ether, ethyl vinyl ether, hexanediol divinyl ether, hydroxybutyl vinyl ether, methyl vinyl ether, triethylene glycol divinyl ether, triethylene glycol methyl vinyl ether ~~and or~~ or trimethylolpropane trivinyl ether.

4. (Currently amended) Curable resin ~~compositions~~ composition according to Claim 3, ~~characterised in that~~ wherein the vinyl ether monomer is hydroxybutyl vinyl ether or triethylene glycol divinylether.

5. (Canceled)

6. (Currently amended) Curable resin ~~compositions~~ composition according to Claim 5 ~~characterised in that~~ 1, wherein the (meth)acrylate-containing resin is a said vinyl ester urethane resin.

7. (Currently amended) Curable resin ~~compositions~~ composition according to Claim 1, ~~characterised in that~~ wherein the amount of vinyl ether monomer is 0.5-50 wt.%, relative to the weight of the total resin composition.

8. (Currently amended) Curable resin ~~compositions~~ composition according to Claim 7, ~~characterised in that~~ wherein the amount of vinyl ether monomer is 5-20 wt. %, relative to the weight of the total resin composition.

9. (Currently amended) Process for the preparation of a curable resin composition ~~based on~~ comprising an unsaturated prepolymer, a vinyl ether monomer that can be cross-linked with it and one or more other monomers, ~~characterised in that~~ wherein the resin composition is prepared by blending

(1) an unsaturated prepolymer comprising a (meth)acrylate-containing resin selected from the group consisting of vinyl esters resins and vinyl ester urethane resins obtained by reacting an isocyanate, a polyol and a hydroxyl-terminated ester of (meth)acrylic acid, and having an acid number of less than 10 mg of KOH per g,

(2) a vinyl ether monomer having a general structure according to formula (I) or (II):



or



where

A represents hydrogen or an alkyl group with 1-3 C atoms, and where, if there is more than one A, the individual A groups may be the same or different,

R either represents an aliphatic group, optionally branched, with 1-20 C atoms, which may also contain a cyclohexyl group and optionally in the carbon chain also one or more O and/or S atoms, which group may be substituted with a functional group chosen from either a hydroxyl group or an amino group, optionally substituted with one or two alkyl groups with 1-3 C atoms,

or represents a polyethylene glycol or a polypropylene glycol with an average chain length of 2 to 10 glycol units, optionally with an aliphatic group with 1-5 C atoms attached to the chain's free hydroxyl group and

R' either is a residual group that corresponds to an aliphatic group, optionally branched, with 2-20 C atoms, which may also contain a 1,4- dimethylenecyclohexyl group, or represents a polyethylene glycol or a polypropylene glycol with an average chain length of 2 to 10 glycol units

and

n is 1,2,3 or 4,

(3) one or more other monomers

(4) together with any fillers and/or additives that may be required, after which the resin composition can be cured by adding a radical-forming system that is unstable in the temperature range from -20°C to +110°C.

10. (Canceled)

11. (Canceled)

12. (New) Curable resin composition according to claim 1, wherein the (meth)acrylate-containing resin is said vinyl ester resin.

13. (New) Curable resin composition according to claim 1, wherein the (meth)acrylate-containing resin further comprises an unsaturated polyester prepolymer.

14. (New) Curable resin composition according to claim 1, further comprising a radical-forming system that is unstable in the temperature range from -20°C to +110°C.

15. (New) Method for production of a molded part or structural material, comprising curing the curable resin composition according to claim 1 to form a molded part or structural material having a thickness of at least 1 millimeter.

16. (New) Method for production of a molded part or structural material according to claim 15, which comprising curing the curable resin composition in the presence of a radical-forming system which is unstable in the temperature range from -20 °C to +110 °C.

17. (New) Method for production of molded parts or structural materials according to claim 16, which comprises curing the curable resin composition in the presence of said radical-forming system and an accelerator.

18. (New) Method for production of a molded part or structural material, comprising curing the curable resin composition obtained according to the process of claim 9 to form a molded part or structural material having a thickness of at least 1 millimeter.

19. (New) Method for production of a molded part or structural material according to claim 18, which comprises curing the curable resin composition in the presence of a radical-forming system which is unstable in the temperature range from -20 °C to +110 °C.

20. (New) Method for production of molded parts or structural materials according to claim 19, which comprises curing the curable resin composition in the presence of said radical-forming system and an accelerator.

21. (New) A cured resin composition obtained by curing the curable resin composition according to claim 1.

22. (New) Flooring material comprising the cured resin composition according to claim 21, and having a thickness of at least 1 millimeter.

23. (New) Roofing material comprising the cured resin composition according to claim 21, and having a thickness of at least 1 millimeter.

24. (New) A rock bolt comprising the cured resin composition according to claim 21, and having a thickness of at least 1 millimeter.